

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A wiring substrate, in which a wiring stacked portion including at least one a-conductor layer including an internal conductor layer and at least one a resin layer is stacked on a principal face of a core substrate including a substantially cylindrical through hole conductor in a through hole extending therethrough and a filling material filling the hollow portion of said through hole, comprising:

a cover-shaped conductor portion covering an end face of said through hole just over a principal face of said core substrate and connected to said through hole conductor; and

an internal conductor layer provided ~~in said wiring stacked portion and across at least one~~ of said on a side of the resin layer ~~from opposite~~ said cover-shaped conductor layer,

wherein a connection portion composed of at least one ~~via-conductors~~ conductor buried in said at least one resin layer brings said cover-shaped conductor portion and said internal conductor layer into conduction, and

~~said wherein none of said~~ via conductors composing said connection portion are provided ~~not~~ above said through hole.

2. (withdrawn): The wiring substrate according to claim 1,

wherein at least two of said resin layer are sandwiched between said cover-shaped conductor layer and said internal conductor layer, and

said via conductor composed of filled vias is buried in each of said resin layer and is stacked substantially concentrically in plurality to construct said connection portion.

3. (currently amended): The wiring substrate according to claim 1, wherein a distance from a center axis of said at least one via conductor constructing said connection portion to an outer edge of said through hole is from 125 μm to 500 μm .

4. (withdrawn): The wiring substrate according to claim 2, wherein a distance from a center axis of said via conductor constructing said connection portion to an outer edge of said through hole is from 125 μm to 500 μm .

5. (currently amended): A wiring substrate comprising:
a core substrate, including a at least one through hole provided through said core substrate which is an insulating substrate, ~~a at least one substantially cylindrical through hole~~
~~conductors~~ conductor which is substantially cylindrical provided on an inner circumference of said at least one through hole, and a filling material filling a hollow portion of said at least one through hole ~~conductors~~;

a first earthing conductor layer provided on at least one principal face of said core substrate and in a shape ~~containing~~ covering an end face of said through hole and having conduction to said at least one through hole conductor;

a plurality of resin layers provided over said first earthing conductor layer;

a transmission line provided between any ~~ones~~ two of said plurality of resin layers and positioned above said first earthing conductor layer;

a second earthing conductor layer provided over said plurality of resin layers and in a shape containing said transmission line; and

a connection portion including ~~either:~~ two or more via conductors buried individually in said plurality of resin layers; ~~or said via conductors and a third earthing conductor layer provided between the same resin layers as said transmission line and having no conduction to said transmission line,~~ said two or more via conductors being provided to bring said first earthing conductor layer and said second earthing conductor layer into conduction,

wherein ~~said~~ none of said via conductors ~~to be connected to said first earthing conductor layer~~ are positioned in ~~said connection portion so as not to be~~ above said at least one through hole.

6. (currently amended): The wiring substrate according to claim 5, wherein ~~either~~ a stacked via structure, in which a plurality of filled vias are concentrically contiguous to each other at a position avoiding that above said through hole; ~~or~~

AMENDMENT UNDER 37 C.F.R. § 1.111
U.S. Appln. No.: 10/787,412

Atty. Docket No. Q80149

~~a structure, in which said third earthing conductor layer is connected between any~~
~~contiguous ones of said filled vias in said stacked via structure~~ is provided.